

WHAT IS CLAIMED IS:

1. A method of manufacturing a member pattern having a patterned member on a substrate, comprising:
  - a first exposure step of exposing a desired  
5 region of a negative type photosensitive material applied to the substrate to light from a first direction;
  - a second exposure step of exposing the desired  
region of the negative type photosensitive material  
10 to light from a second direction opposite to said first direction;
  - a development step of performing development after said exposure steps to form a precursor pattern of said member; and  
15 a step of baking said precursor pattern.
2. The method of manufacturing a member pattern according to Claim 1, wherein said negative type photosensitive material is applied to extend over a  
20 member previously disposed on said substrate and said substrate.
3. The method of manufacturing a member pattern according to Claim 2, wherein the member previously  
25 disposed on said substrate has a higher optical reflectance than said substrate.

4. The method of manufacturing a member pattern according to Claim 2, wherein the member previously disposed on said substrate is a member that is formed in a process involving exposure, development and  
5 baking of a photosensitive material.

5. The method of manufacturing a member pattern according to Claim 2, wherein the member previously disposed on said substrate has an overhanging part in  
10 the cross section thereof.

6. The method of manufacturing a member pattern according to Claim 1, wherein said patterned member is an insulating member, and said insulating member  
15 has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulating member interposed therebetween.

7. A method of manufacturing a member pattern  
20 having a patterned member on a substrate, comprising:  
a first exposure step of exposing a desired region of a negative type photosensitive material applied to the substrate to light from a first direction;  
25 a development step of performing development after said first exposure step to form a precursor pattern of said member;

a second exposure step of exposing the precursor pattern of said member to light from a second direction opposite to said first direction; and

5           a step of baking said precursor pattern after said second exposure step.

8. The method of manufacturing a member pattern according to Claim 7, wherein said negative type  
10       photosensitive material is applied to extend over a member previously disposed on said substrate and said substrate.

9. The method of manufacturing a member pattern  
15       according to Claim 8, wherein the member previously disposed on said substrate has a higher optical reflectance than said substrate.

10. The method of manufacturing a member  
20       pattern according to Claim 8, wherein the member previously disposed on said substrate is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

25           11. The method of manufacturing a member pattern according to Claim 8, wherein the member previously disposed on said substrate has an

overhanging part in the cross section thereof.

12. The method of manufacturing a member  
pattern according to Claim 7, wherein said patterned  
5 member is an insulating member, and said insulating  
member has a contact hole for electrically  
interconnecting paired conductive members stacked on  
said substrate with the insulating member interposed  
therebetween.

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13. A method of manufacturing a wiring  
structure having, on a substrate, a first wiring and  
a second wiring intersecting said first wiring and  
disposed over the first wiring through an insulator,  
15 wherein a process of forming said insulator  
comprises: a first exposure step of exposing a  
desired region of a negative type photosensitive  
insulating material to light from a first direction,  
the negative type photosensitive insulating material  
20 being applied to extend over said substrate and the  
first wiring disposed on the substrate; a second  
exposure step of exposing the desired region of the  
negative type photosensitive insulating material to  
light from a second direction opposite to said first  
25 direction; a step of performing development after  
said exposure steps to form a precursor pattern of  
said insulator; and a step of baking the precursor

pattern of said insulator.

14. The method of manufacturing a wiring structure according to Claim 13, wherein said first  
5 wiring is a member which has a higher optical reflectance than said substrate.

15. The method of manufacturing a wiring structure according to Claim 13, wherein said first  
10 wiring is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

16. The method of manufacturing a wiring  
15 structure according to Claim 13, wherein said first wiring has an overhanging part in the cross section thereof.

17. The method of manufacturing a wiring  
20 structure according to Claim 13, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulator interposed therebetween.

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18. A method of manufacturing an electron source having a wiring structure and an electron

emitting element connected to said wiring structure,  
the wiring structure having, on a substrate, a first  
wiring and a second wiring intersecting said first  
wiring and disposed over the first wiring through an  
5 insulator, wherein said wiring structure is  
manufactured according to the method in Claim 13.

19. A method of manufacturing an image display  
device having a wiring structure, an electron  
10 emitting element connected to said wiring structure  
and an image display member for displaying an image  
by irradiation with electrons from said electron  
emitting element, the wiring structure having, on a  
substrate, a first wiring and a second wiring  
15 intersecting said first wiring and disposed over the  
first wiring through an insulator, wherein said  
wiring structure is manufactured according to the  
method in Claim 13.

20 20. A method of manufacturing a wiring  
structure having, on a substrate, a first wiring and  
a second wiring intersecting said first wiring and  
disposed over the first wiring through an insulator,  
wherein a process of forming said insulator  
25 comprises: a first exposure step of exposing a  
desired region of a negative type photosensitive  
insulating material to light from a first direction,

the negative type photosensitive insulating material  
being applied to extend over said substrate and the  
first wiring disposed on the substrate; a step of  
performing development after said first exposure step  
5 to form a precursor pattern of said insulator; a  
second exposure step of exposing the precursor  
pattern of said insulator to light from a second  
direction opposite to said first direction; and a  
step of baking the precursor pattern after said  
10 second exposure step.

21. The method of manufacturing a wiring  
structure according to Claim 20, wherein said first  
wiring is a member which has a higher optical  
15 reflectance than said substrate.

22. The method of manufacturing a wiring  
structure according to Claim 20, wherein said first  
wiring is a member that is formed in a process  
20 involving exposure, development and baking of a  
photosensitive material.

23. The method of manufacturing a wiring  
structure according to Claim 20, wherein said first  
25 wiring has an overhanging part in the cross section  
thereof.

24. The method of manufacturing a wiring structure according to Claim 20, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on  
5 said substrate with the insulator interposed therebetween.

25. A method of manufacturing an electron source having a wiring structure and an electron  
10 emitting element connected to said wiring structure, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is  
15 manufactured according to the method in Claim 20.

26. A method of manufacturing an image display device having a wiring structure, an electron emitting element connected to said wiring structure  
20 and an image display member for displaying an image by irradiation with electrons from said electron emitting element, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the  
25 first wiring through an insulator, wherein said wiring structure is manufactured in the method according to Claim 20.